

IN THE CLAIMS

1. (Currently Amended) A semiconductor substrate processing apparatus comprising:
 - a frame;
 - a semiconductor substrate support to support a semiconductor substrate, the semiconductor substrate having a central axis;
 - a dispense head connected to the frame to dispense a semiconductor processing fluid onto the semiconductor substrate; and
 - a catch cup section attached to the frame having an inner surface and an outer surface, at least a portion of the inner surface not facing towards the central axis of the semiconductor substrate, wherein the catch cup further comprises a lip extending from the inner surface thereof towards the central axis of the semiconductor substrate, and wherein the lip is angled such that an inner portion of the lip is higher than an outer portion of the lip.
2. (Original) The semiconductor substrate processing apparatus of claim 1, wherein a line normal to and extending only away from the portion of the inner surface does not intersect the central axis of the semiconductor substrate.
3. (Cancelled)
4. (Currently Amended) The semiconductor substrate processing apparatus of claim 1, wherein a [[3]] 2, wherein the lip further comprises an upper surface and a lower surface, at least a portion of the upper surface of the lip facing away from the central axis of the semiconductor substrate.

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